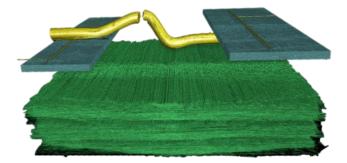
Composite Structures in Lightweight Photovoltaic Modules for Vehicle Integration

Rik Van Dyck, Bin Luo, Tom Borgers, Jonathan Govaerts, Jef Poortmans, Aart W. van Vuure





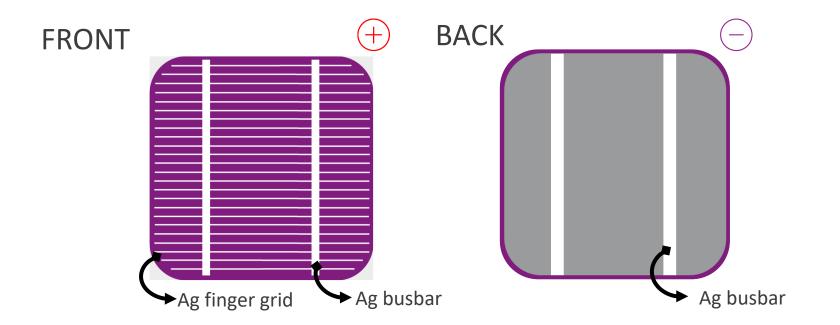


- I. Standard photovoltaic module production
- 2. Vehicle-integrated PV:A Motivation for weight reduction
- 3. Reliability assessment
- 4. Results
- 5. Conclusions



Standard PV Module Assembly

Standard cells for standard modules





Cell interconnection

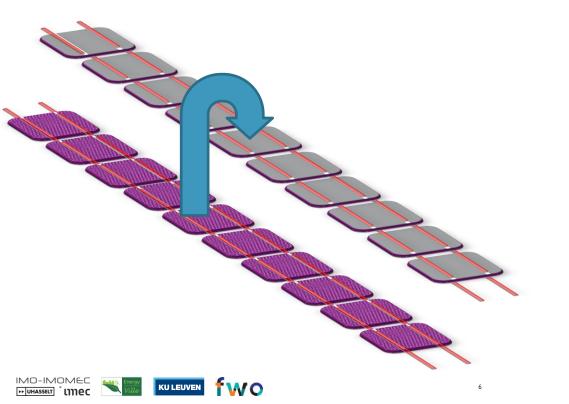
- **Cells soldered in series connection** using ribbons going from the front to back of neighboring cells
- Ribbons: Cu core with SnPb(Ag) coating

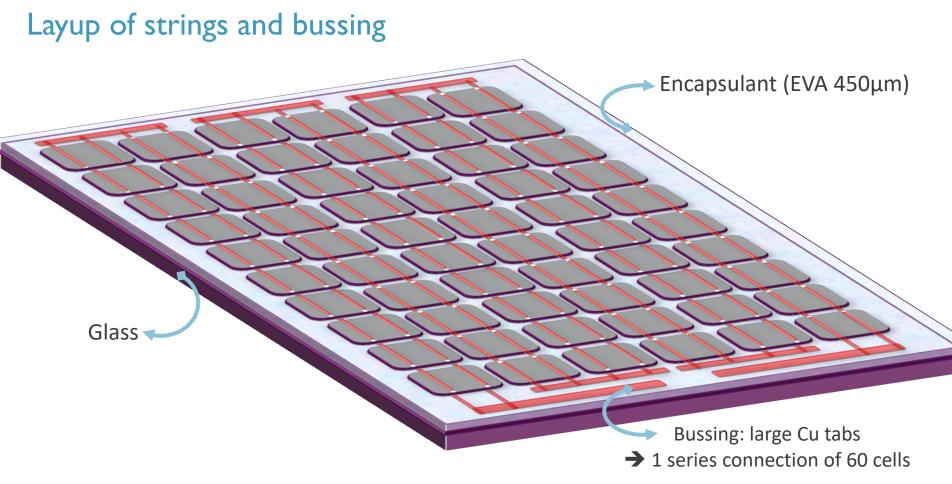
Improve performance by

optimal number and size of busbars and ribbon are a shading vs. series loss trade-off



Soldering (tabbing) into strings (stringing)







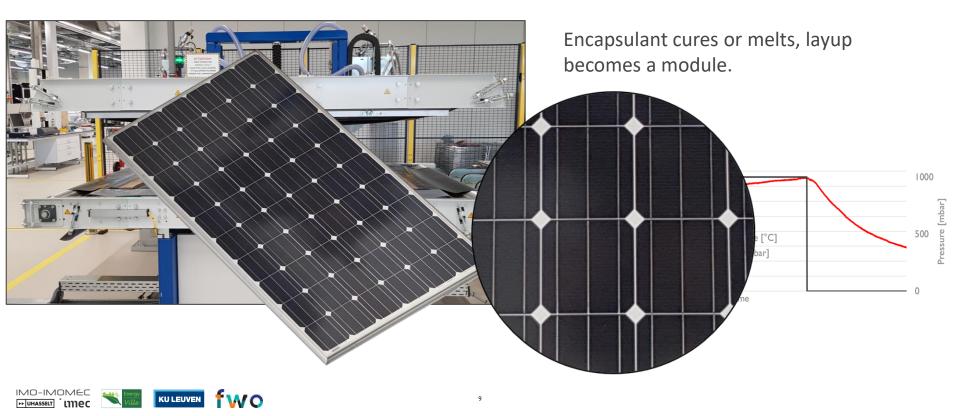
Module layup

Encapsulant (EVA 450 μm)

Backsheet PET/PVF/PA/AI/PVDF/... or glass



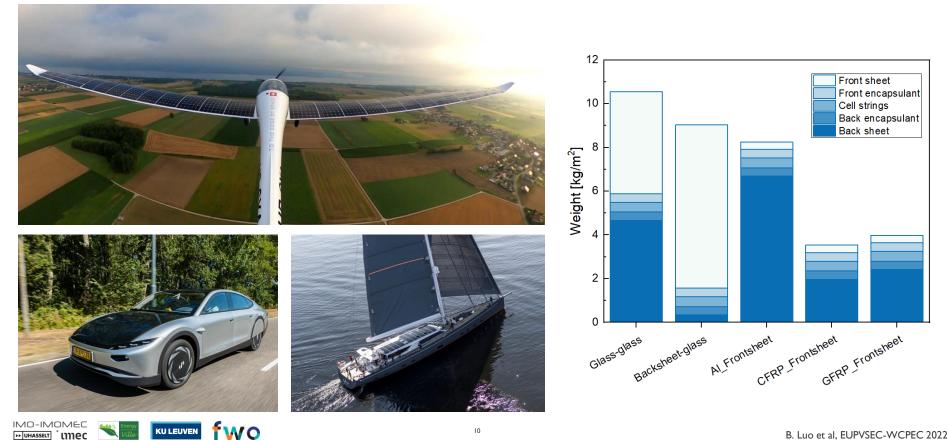
Module lamination



Motivation for lightweight modules

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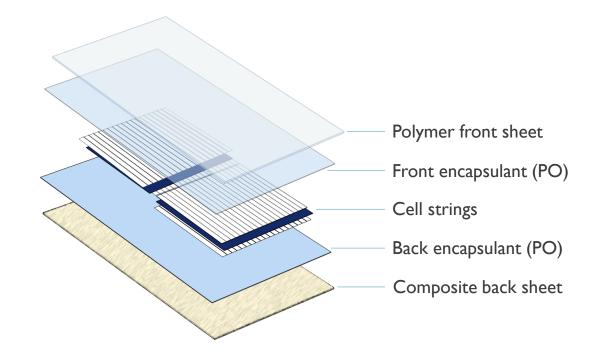


Reliability assasment of photovoltaics

- Hail impact testing
- Thermal cycling



Module exploded view





Fiber reinforced polypropylene backsheet

- Lamination of 8 plies
 - [0/90] unidirectional fibers
 - 60 w% glass fibers and 50 w% carbon fibers
- Glass and carbon fiber reinforcements

MO



GFPP backsheet

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imec

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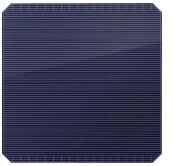
CFPP backsheet

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Fiber reinforced polymer backsheet [0/90]_s

Cell interconnection

- Cell interconnection foil
 - I8 Cu wires with SnBiAg-coating
 - Polyolefin-based carrier foil



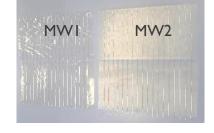
Solar cell frontside

▶▶ UHASSELT

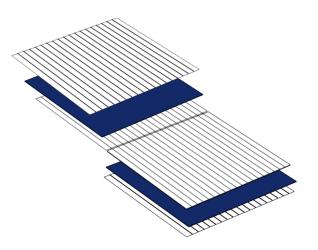
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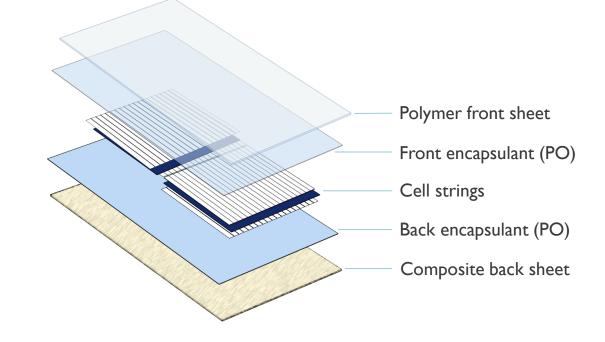
two







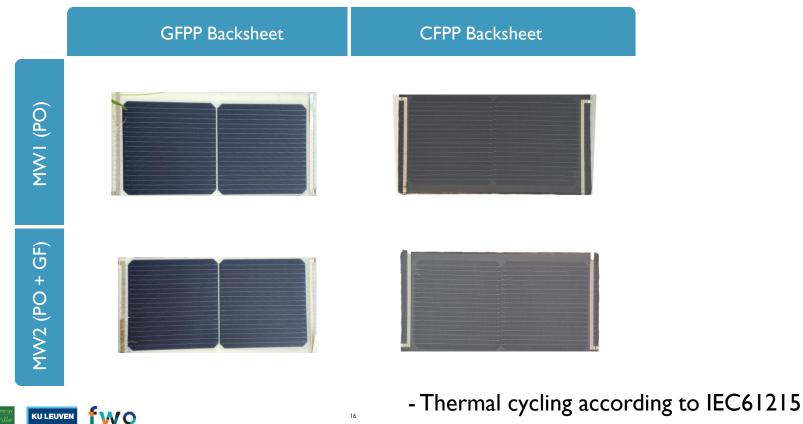
- Module layup and lamination
- During lamination:
 - Encapsulation
 - Soldering



Experimental matrix

IMO-IMOMEC

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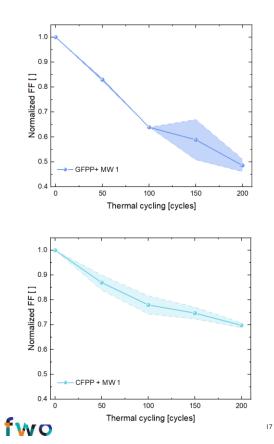
16

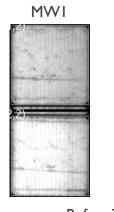
Reliability assessment Thermal cycling (-40 to 85 °C, IEC 61215)



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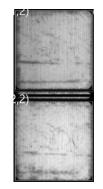
IMO-IMOMEC



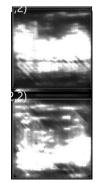


Before TC

Before TC



MWI



After TC 200



After TC 200

Reliability assessment Thermal cycling (-40 to 85 °C, IEC 61215)

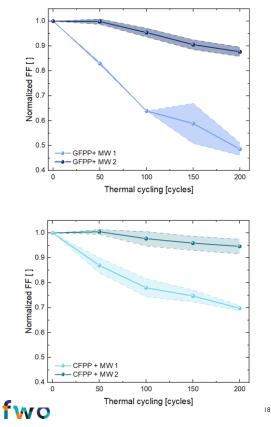


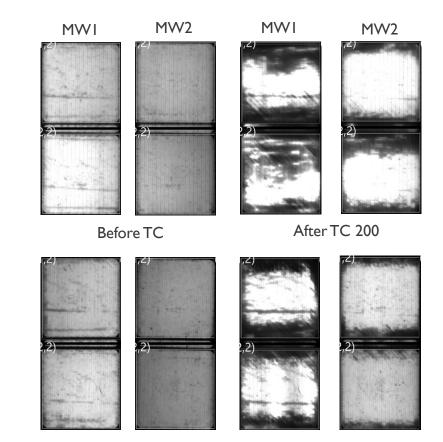


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Before TC

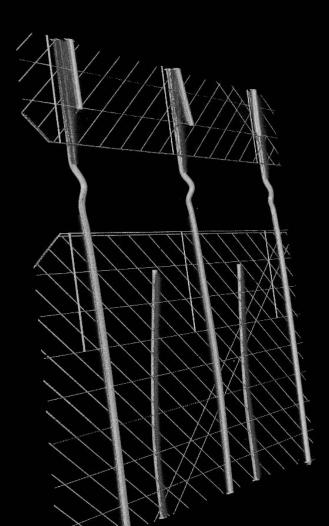
After TC 200

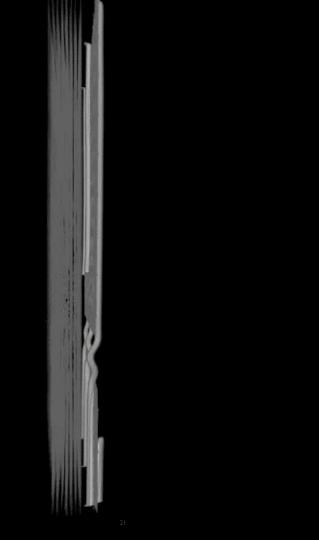
3D Micro-computed tomography

- Non-destructive analyzing technique
- Multiple X-ray scans of rotating sample, followed by reconstruction to create 3D volume rendering
- Voxel (3D Pixel) sized as low as 1-3 µm
- Resolution depends on sample size

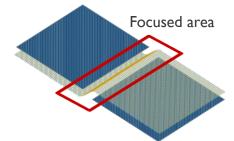


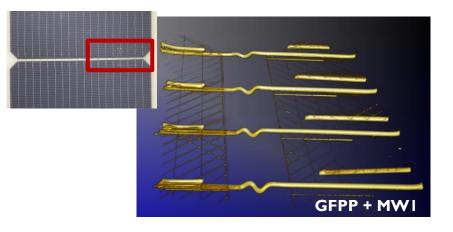


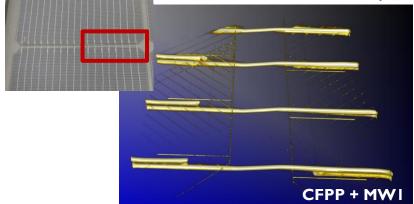




Reliability assessment and characterization Micro-computed tomography (µ-CT) imaging







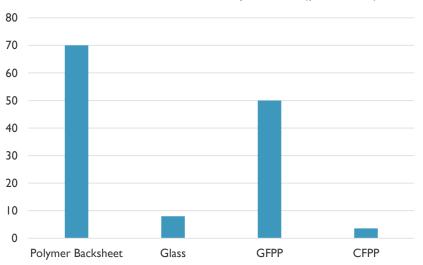
• Wire deformation between cells due to thermal strain



Reduced thermal strain

IMO-IMOMEC

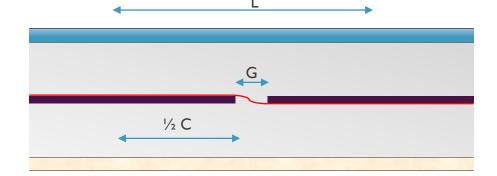
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Coefficient of Thermal Expansion (μ m/m°C)



$$\Delta G = L \cdot \alpha_{backsheet} - C \cdot \alpha_{Si}$$

GFPP: $\Delta G = 7.5 \ \mu m/ \ ^{\circ}C$
CFPP: $\Delta G = 0.2 \ \mu m/ \ ^{\circ}C$

23



- Lightweight modules using a multi-wire interconnection are prone to degradation due to thermo-mechanical stress
- Decreasing the backsheet CTE improves the reliability
- Using carbon fibre reinforcement in a polymer backsheet increases module reliability
- Further investigation using FEM is ongoing



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Thanks for your attention!!

Questions & discussion

